## Materials Declaration

| | |
|---|---|
| **Package** | MSOP |
| **Body Size** | 3 X 3 |
| **LeadCount** | 10 |
| **Option** | Pb-Free |

### Molding Compound

| Item | % of Compound | Weight (g) | PPM |
|---|---|---|---|
| Epoxy resin | 10 | 9.57 E-04 | 33859 |
| SiO2 Filler | 85 | 8.13 E-03 | 287806 |
| Phenol Resin | 3 | 2.87 E-04 | 10158 |
| Antimony_Sb2O3 | 1.5 | 1.44 E-04 | 5079 |
| Brominated Resin | 0.5 | 4.78 E-05 | 1693 |

### Leadframe

| Item | % of Leadframe | Weight (g) | PPM |
|---|---|---|---|
| Cu | 97.5 | 1.61 E-02 | 571064 |
| Fe | 2.35 | 3.89 E-04 | 13764 |
| P | 0.03 | 4.97 E-06 | 176 |
| Zn | 0.12 | 1.99 E-05 | 703 |

### Internal Leadframe Plating

| | % of Plating | Weight (g) | PPM |
|---|---|---|---|
| Ag | 100 | 3.00 E-04 | 10615 |

### External Leadframe Plating

| Item | % of Plating | Weight (g) | PPM |
|---|---|---|---|
| Sn | 100 | 3.18 E-04 | 11234 |

### Bond Wires

| | % of Wire | Weight (g) | PPM |
|---|---|---|---|
| **Au** | 99.99 | 3.23 E-04 | 11411 |

### Chip

| | % of Chip | Weight (g) | PPM |
|---|---|---|---|
| Si | **100** | 9.49 E-04 | 33578 |

### Die Attach

| Item | % of Die Attach | Weight (g) | PPM |
|---|---|---|---|
| Resin | 25 | 7.46 E-05 | 2639 |
| Ag Filler | 75 | 2.24 E-04 | 7916 |

### Package Totals

| Weight (g) | PPM |
|---|---|
| **2.83 E-02** | 1000000 |

### Molding Compound

| Item | PPM | Method |
|---|---|---|
| Pb | <2 | US EPA method #3052 & 6010E |
| Cd | Not Detected | BS EN 1122:2001 ICP AES |
| Hg | <2 | US EPA method #3052 & 7471A |
| Cr+6 | <2 | US EPA method #3060A & 6010E |

### Die Attach Paste

| Item | PPM | Method |
|---|---|---|
| Pb | <5 | ICP AES |
| Cd | <5 | ICP AES |
| Hg | <5 | ICP AES |
| Cr+6 | <5 | ICP AES |
| PBB | Not Detected | |
| PBDE | Not Detected | |

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# Materials Declaration

| | |
|---|---|
| **Package** | MINI_SO - COL |
| **Body Size** | |
| **LeadCount** | 10 |
| **Option** | Halide-free, Pb-free |

**Molding Compound**

| Item | % of Compound | Weight (g) | PPM |
|---|---|---|---|
| Silica | 86.0 | 1.11 E-02 | 449933 |
| Epoxy Resin | 7.5 | 9.65 E-04 | 39238 |
| Phenol Resin | 4.0 | 5.15 E-04 | 20927 |
| Epoxy Cresol Novolac | 2.0 | 2.57 E-04 | 10464 |
| Carbon Black | 0.5 | 6.44 E-05 | 2616 |
| Subtotal | 100.0 | 1.29 E-02 | 523178 |

**Molding Compound**

| Item | PPM | Method |
|---|---|---|
| Pb | Not Detected | Draft IEC62321. ICP-OES. |
| Cd | Not Detected | Draft IEC62321. ICP-OES. |
| Hg | Not Detected | Draft IEC62321. ICP-OES. |
| Cr+6 | Not Detected | Draft IEC62321. UV-VIS. |
| PBB | Not Detected | Draft IEC62321. GC-MSD. |
| PBDE | Not Detected | Draft IEC62321. GC-MSD. |

**Leadframe**

| Item | % of Leadframe | Weight (g) | PPM |
|---|---|---|---|
| Copper | 97.5 | 9.54 E-03 | 387662 |
| Iron | 2.35 | 2.23 E-04 | 9079 |
| Zinc | 0.12 | 1.24 E-05 | 503 |
| Phosphorus | 0.03 | 2.38 E-06 | 97 |
| Subtotal | 100 | 9.77 E-03 | 397341 |

**Die Attach Paste**

| Item | PPM | Method |
|---|---|---|
| Pb | Not Detected | Draft IEC62321. ICP-OES. |
| Cd | Not Detected | Draft IEC62321. ICP-OES. |
| Hg | Not Detected | Draft IEC62321. ICP-OES. |
| Cr+6 | Not Detected | Draft IEC62321. UV-VIS. |
| PBB | Not Detected | Draft IEC62321. GC-MSD. |
| PBDE | Not Detected | Draft IEC62321. GC-MSD. |

**Internal/External Leadframe Plating**

| Item | % of Plating | Weight (g) | PPM |
|---|---|---|---|
| Nickel | 90.91 | 1.14 E-04 | 4628 |
| Palladium | 7.91 | 9.90 E-06 | 402 |
| Gold | 1.19 | 1.49 E-06 | 60 |
| Subtotal | 100.00 | 1.25 E-04 | 5091 |

**Bond Wires**

| | % of Wire | Weight (g) | PPM |
|---|---|---|---|
| Gold | 99.99 | 3.10 E-04 | 12601 |

**Chip**

| | % of Chip | Weight (g) | PPM |
|---|---|---|---|
| Doped Silicon | 100 | 1.00 E-03 | 40651 |

**Die Attach**

| Item | % of Die Attach | Weight (g) | PPM |
|---|---|---|---|
| Epoxy Resin | 31 | 1.61 E-04 | 6553 |
| Metal Oxide | 31 | 1.61 E-04 | 6553 |
| Glycol Ethers | 22 | 1.14 E-04 | 4650 |
| Silica | 8 | 4.16 E-05 | 1691 |
| Curing agent & hardener | 8 | 4.16 E-05 | 1691 |
| Subtotal | 100 | 5.20 E-04 | 21139 |

**Package Totals**

| Weight (g) | PPM |
|---|---|
| **2.46 E-02** | 1000000 |

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any inaccuracy of such information.

# Materials Declaration

| | |
|---|---|
| **Package** | MSOP |
| **Body Size** | 3 X 3 |
| **LeadCount** | 10 |
| **Option** | Sn/Pb |

### Molding Compound

| Item | % of Compound | Weight (g) | PPM |
|---|---|---|---|
| Epoxy resin | 10 | 9.57 E-04 | 33859 |
| SiO2 Filler | 85 | 8.13 E-03 | 287806 |
| Phenol Resin | 3 | 2.87 E-04 | 10158 |
| Antimony_Sb2O3 | 1.5 | 1.44 E-04 | 5079 |
| Brominated Resin | 0.5 | 4.78 E-05 | 1693 |

### Leadframe

| Item | % of Leadframe | Weight (g) | PPM |
|---|---|---|---|
| Cu | 97.5 | 1.61 E-02 | 571064 |
| Fe | 2.35 | 3.89 E-04 | 13764 |
| P | 0.03 | 4.97 E-06 | 176 |
| Zn | 0.12 | 1.99 E-05 | 703 |

### Internal Leadframe Plating

| | % of Plating | Weight (g) | PPM |
|---|---|---|---|
| Ag | 100 | 3.00 E-04 | 10615 |

### External Leadframe Plating

| Item | % of Plating | Weight (g) | PPM |
|---|---|---|---|
| Sn | 85 | 2.70 E-04 | 9549 |
| Pb | 15 | 4.76 E-05 | 1685 |

### Bond Wires

| | % of Wire | Weight (g) | PPM |
|---|---|---|---|
| **Au** | 99.99 | 3.23 E-04 | 11411 |

### Chip

| | % of Chip | Weight (g) | PPM |
|---|---|---|---|
| Si | **100** | 9.49 E-04 | 33578 |

### Die Attach

| Item | % of Die Attach | Weight (g) | PPM |
|---|---|---|---|
| Resin | 25 | 7.46 E-05 | 2639 |
| Ag Filler | 75 | 2.24 E-04 | 7916 |

### Package Totals

| Weight (g) | PPM |
|---|---|
| **2.83 E-02** | 1000000 |

### Molding Compound

| Item | PPM | Method |
|---|---|---|
| Pb | <2 | US EPA method #3052 & 6010E |
| Cd | Not Detected | BS EN 1122:2001 ICP AES |
| Hg | <2 | US EPA method #3052 & 7471A |
| Cr+6 | <2 | US EPA method #3060A & 6010E |

### Die Attach Paste

| Item | PPM | Method |
|---|---|---|
| Pb | <5 | ICP AES |
| Cd | <5 | ICP AES |
| Hg | <5 | ICP AES |
| Cr+6 | <5 | ICP AES |
| PBB | Not Detected | |
| PBDE | Not Detected | |

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